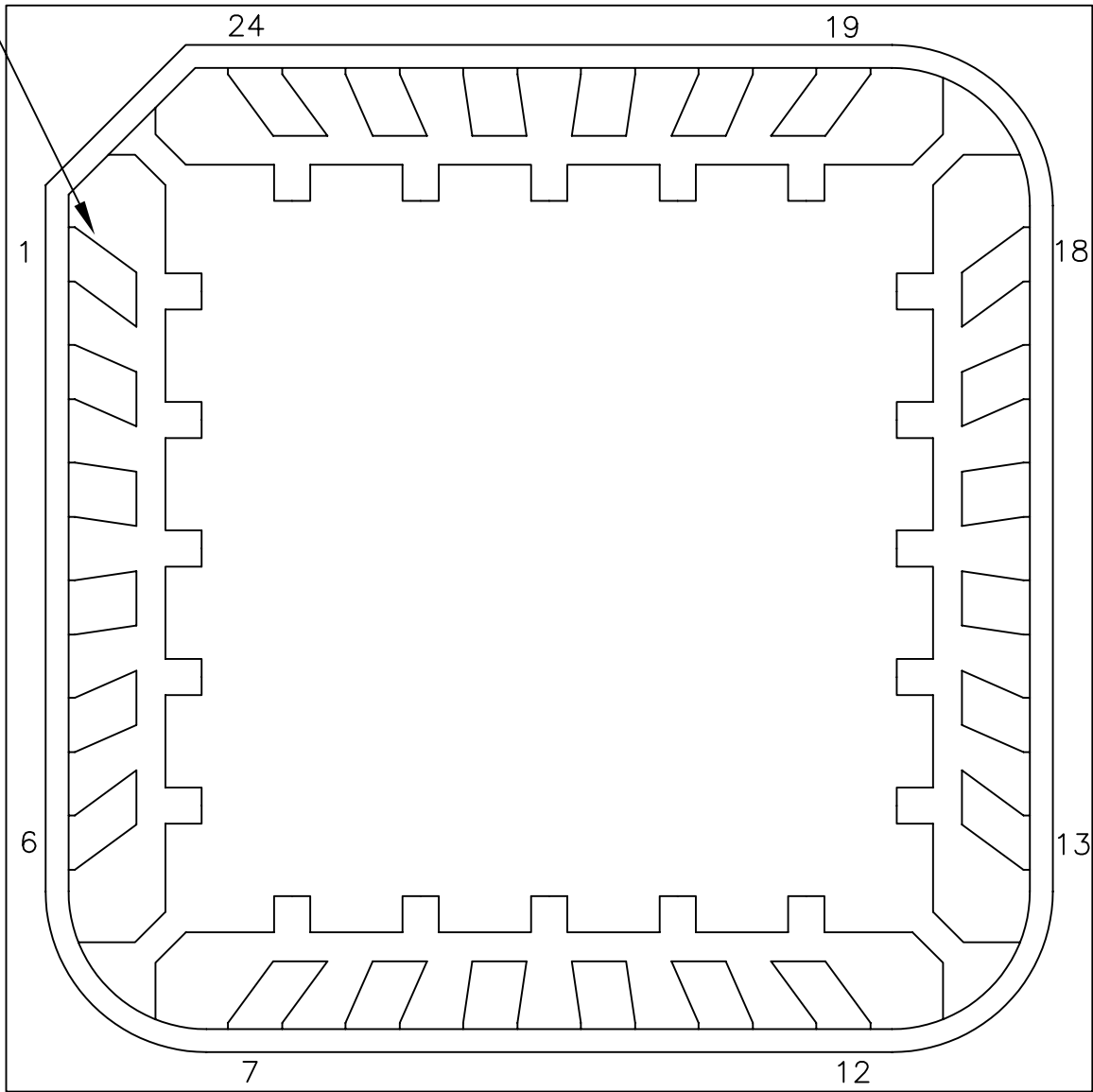


BONDING PAD #1



| | | | | | | | | | |
|--|--------------|-------|------------------|---|-----------------|---|----------|---------------------------------------|-----|
| DEVICE TYPE: | | | | <p align="center">SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006</p> | | | | | |
| CUSTOMER: | | | DIE SIZE: | | | | | | |
| WIRE TYPE/ SIZE: | | | NO. OF WIRES: | | | | | | |
| <p>THIRD ANGLE PROJECTION</p> | REVISIONS | | | | | <p align="center">24 Lead 6mm x 6mm MLP Open-Pak Bonding Diagram</p> | | | |
| | ECN NO. | DATE | DESCRIPTION | APPROVED | | | | | |
| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING | | 10594 | 1/20/06 | PRODUCTION RELEASE | D.BENANDO | | | | |
| DRAWN BY | W. GRIFFITTS | DATE | 1/20/06 | PACKAGE SIZE: | 6.00mm x 6.00mm | | SIZE | PART NO. | REV |
| APP BY | P. FLASKERUD | DATE | 1/20/06 | DIE PAD SIZE: | 4.24mm x 4.24mm | | A | MLP6X6-24-OP-01 | 1 |
| | | | | SCALE | 26X | | CAD FILE | MLP6X6-24-OP-01-B-R1.DWG SHEET 1 OF 1 | |